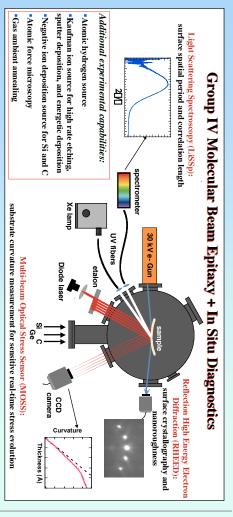
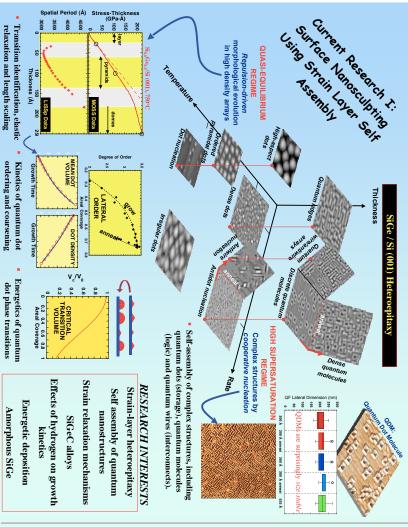
# STRESS EVOLUTION AND NANOMORPHOLOGY DURING THIN FILM DEPOSITION - IN SITU NANOMECHANICS

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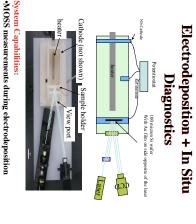
Quantitative stress-strain measurements in-situ of a TEM

deformation processes

Top View

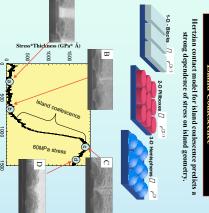
Side View

**TEM studies of Nano-mechanical** 



Three and four point probe electrochemical measurements

Electrodeposition allows for unique studies of the effect of restricted geometries (via selective area growth) on stress and microstructure



# Unpatterned films

Build upon studies of discrete phen

understand stress evolution in blanket films. Thickness (A) Decreased plating rate results in decreased stress

ordering and coarsening

Amorphous SiGe

MEMS-based tensile tester designed for actuation in-situ

in a TEM.

Gauge section located over Bosch hole through the wafer to facilitate plan-view TEM imaging during actuation.

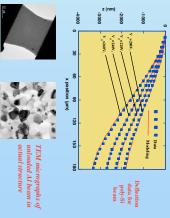
Collaborator: M. De Boer

Ex-situ interferometry is used to characterize the stress-strain response of the MEMS structures.





ed from finite element alysis of data



Developing capability to build device using both lift-off masks and electroplating to allow study of nano-structured Al, Ni, and Cu.